

**TC74AC112P, TC74AC112F, TC74AC112FN**

**DUAL J – K FLIP FLOP WITH PRESET AND CLEAR**

The TC74AC112 is an advanced high speed CMOS DUAL J-K FLIP FLOP fabricated with silicon gate and double-layer metal wiring C<sup>2</sup>MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

In accordance with the logic level given J and K input this device changes state on negative going transition of the clock pulse.  $\overline{\text{CLEAR}}$  and  $\overline{\text{PRESET}}$  are independent of the clock and accomplished by a low logic level on the corresponding input. All inputs are equipped with protection circuits against static discharge or transient excess voltage.

**FEATURES :**

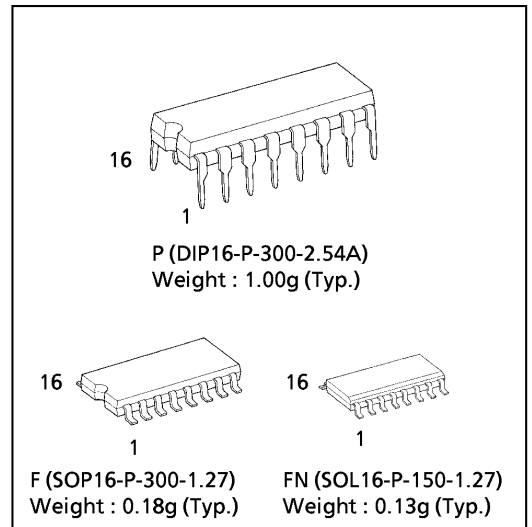
- High Speed..... $f_{\text{MAX}} = 170\text{MHz}$  (typ.)  
at  $V_{\text{CC}} = 5\text{V}$
- Low Power Dissipation..... $I_{\text{CC}} = 4\mu\text{A}(\text{Max.})$  at  $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}}$  (Min.)
- Symmetrical Output Impedance... $|I_{\text{OH}}| = I_{\text{OL}} = 24\text{mA}(\text{Min.})$   
Capability of driving  $50\Omega$  transmission lines.
- Balanced Propagation Delays..... $t_{\text{pLH}} \approx t_{\text{pHL}}$
- Wide Operating Voltage Range... $V_{\text{CC}}(\text{opr}) = 2\text{V} \sim 5.5\text{V}$
- Pin and Function Compatible with 74F112

**TRUTH TABLE**

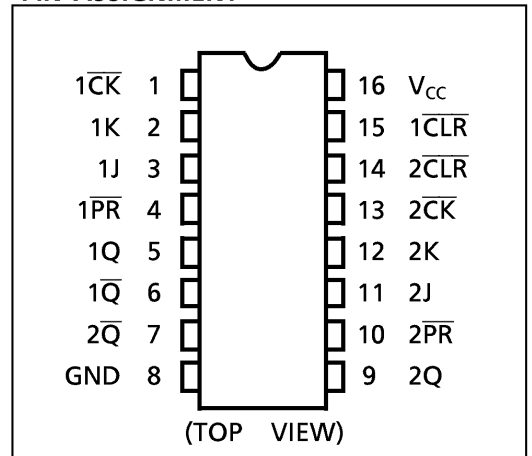
INPUTS					OUTPUTS		FUNCTION
CLR	PR	J	K	$\overline{\text{CK}}$	Q	$\overline{\text{Q}}$	
L	H	X	X	X	L	H	CLEAR
H	L	X	X	X	H	L	PRESET
L	L	X	X	X	H	H	
H	H	L	L	$\downarrow$	$Q_n$	$\overline{Q}_n$	NO CHANGE
H	H	L	H	$\downarrow$	L	H	
H	H	H	L	$\downarrow$	H	L	
H	H	H	H	$\downarrow$	$\overline{Q}_n$	$Q_n$	TOGGLE
H	H	X	X	$\uparrow$	$Q_n$	$\overline{Q}_n$	NO CHANGE

X : Don't Care

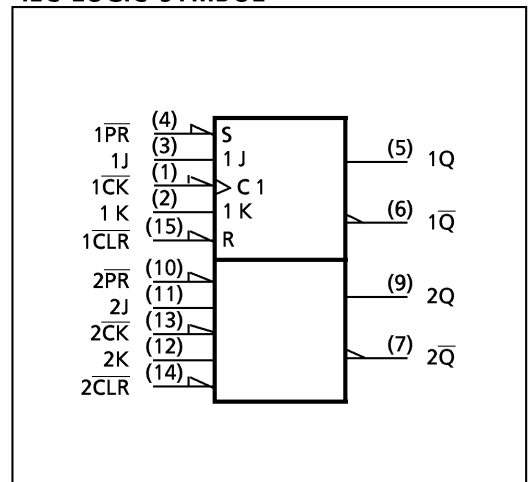
(Note) The JEDEC SOP (FN) is not available in Japan.



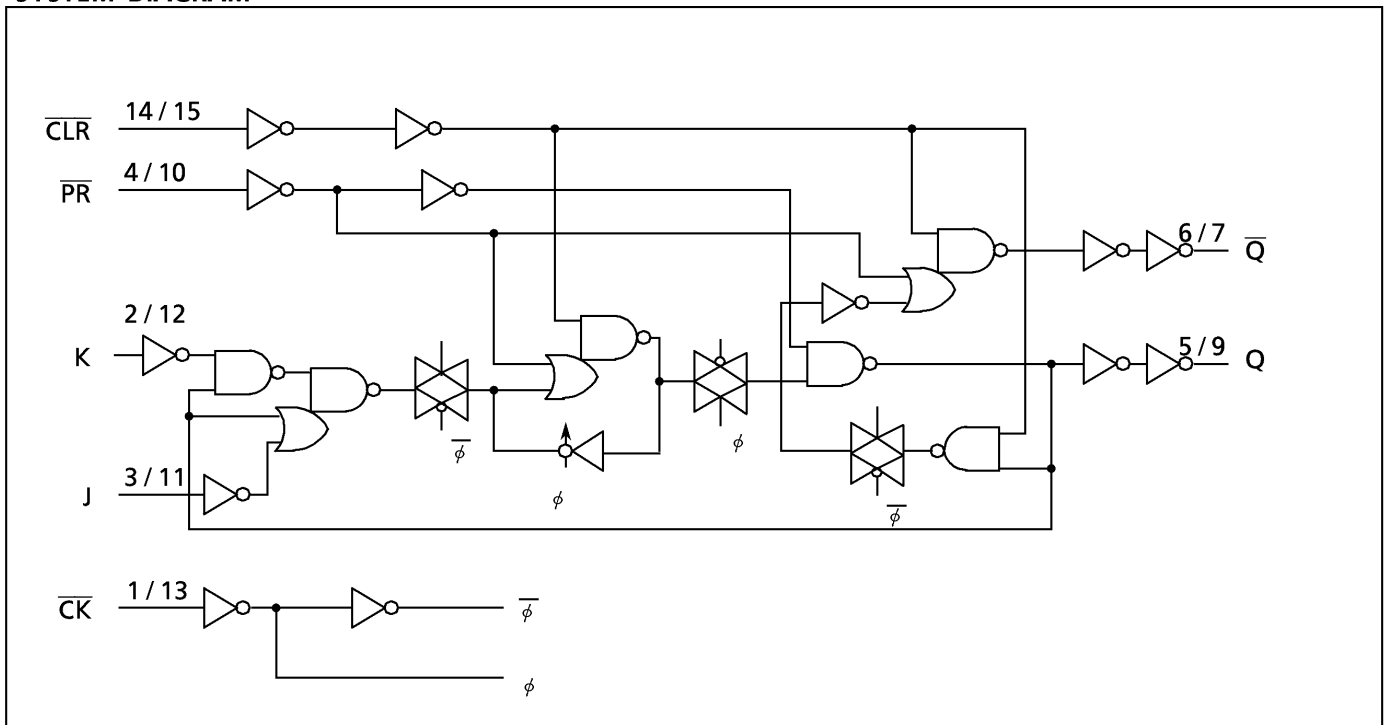
**PIN ASSIGNMENT**



**IEC LOGIC SYMBOL**



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	$V_{CC}$	-0.5~7.0	V
DC Input Voltage	$V_{IN}$	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	$V_{OUT}$	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	$I_{IK}$	± 20	mA
Output Diode Current	$I_{OK}$	± 50	mA
DC Output Current	$I_{OUT}$	± 50	mA
DC $V_{CC}$ /Ground Current	$I_{CC}$	± 100	mA
Power Dissipation	$P_D$	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	$T_{stg}$	-65~150	°C

\*500mW in the range of  $T_a = -40^{\circ}C \sim 65^{\circ}C$ . From  $T_a = 65^{\circ}C$  to  $85^{\circ}C$  a derating factor of  $-10mW/^{\circ}C$  should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	$V_{CC}$	2.0~5.5	V
Input Voltage	$V_{IN}$	0~ $V_{CC}$	V
Output Voltage	$V_{OUT}$	0~ $V_{CC}$	V
Operating Temperature	$T_{opr}$	-40~85	°C
Input Rise and Fall Time	$dt/dV$	0~ 100 ( $V_{CC} = 3.3 \pm 0.3V$ ) 0~ 20 ( $V_{CC} = 5 \pm 0.5V$ )	ns/V

**DC ELECTRICAL CHARACTERISTICS**

PARAMETER	SYMBOL	TEST CONDITION	V <sub>CC</sub> (V)	Ta = 25°C			Ta = -40~85°C		UNIT	
				MIN.	TYP.	MAX.	MIN.	MAX.		
High - Level Input Voltage	V <sub>IH</sub>		2.0 3.0 5.5	1.50 2.10 3.85	— — —	— — —	1.50 2.10 3.85	— — —	V	
Low - Level Input Voltage	V <sub>IL</sub>		2.0 3.0 5.5	— — —	— — —	0.50 0.90 1.65	— — —	0.50 0.90 1.65	V	
High - Level Output Voltage	V <sub>OH</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -50μA	2.0	1.9	2.0	—	1.9	—	V
				3.0	2.9	3.0	—	2.9	—	
				4.5	4.4	4.5	—	4.4	—	
				3.0	2.58	—	—	2.48	—	
				4.5	3.94	—	—	3.80	—	
				5.5	—	—	—	3.85	—	
Low - Level Output Voltage	V <sub>OL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50μA	2.0	—	0.0	0.1	—	0.1	V
				3.0	—	0.0	0.1	—	0.1	
				4.5	—	0.0	0.1	—	0.1	
				3.0	—	—	0.36	—	0.44	
				4.5	—	—	0.36	—	0.44	
				5.5	—	—	—	—	1.65	
Input Leakage Current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	±0.1	—	±1.0	μA	
Quiescent Supply Current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	4.0	—	40.0		

\* : This spec indicates the capability of driving 50Ω transmission lines.  
One output should be tested at a time for a 10ms maximum duration.

**TIMING REQUIREMENTS (Input t<sub>r</sub> = t<sub>f</sub> = 3ns)**

PARAMETER	SYMBOL	TEST CONDITION	V <sub>CC</sub> (V)	Ta = 25°C	Ta = -40~85°C	UNIT
				LIMIT	LIMIT	
Minimum Pulse Width ( $\overline{CK}$ )	t <sub>W(L)</sub>		3.3 ± 0.3	7.5	7.5	ns
	t <sub>W(H)</sub>		5.0 ± 0.5	5.0	5.0	
Minimum Pulse Width ( $\overline{CLR}$ , $\overline{PR}$ )	t <sub>W(L)</sub>		3.3 ± 0.3	7.0	7.0	
			5.0 ± 0.5	5.0	5.0	
Minimum Set - up Time	t <sub>s</sub>		3.3 ± 0.3	11.0	11.0	
			5.0 ± 0.5	6.0	6.0	
Minimum Hold Time	t <sub>h</sub>		3.3 ± 0.3	0.0	0.0	
			5.0 ± 0.5	0.0	0.0	
Minimum Removal Time ( $\overline{CLR}$ , $\overline{PR}$ )	t <sub>rem</sub>		3.3 ± 0.3	3.0	3.0	
			5.0 ± 0.5	2.0	2.0	

AC ELECTRICAL CHARACTERISTICS (  $C_L = 50\text{pF}$ ,  $R_L = 500\ \Omega$ , Input  $t_r = t_f = 3\text{ns}$  )

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C			Ta = -40~85°C		UNIT	
			V <sub>CC</sub> (V)	MIN.	TYP.	MAX.	MIN.		MAX.
Propagation Delay Time ( $\overline{\text{CK}} - \text{Q}$ , $\overline{\text{Q}}$ )	$t_{\text{pLH}}$ $t_{\text{pHL}}$		3.3 ± 0.3	—	9.1	15.5	1.0	17.8	ns
			5.0 ± 0.5	—	6.5	9.4	1.0	10.8	
Propagation Delay Time ( $\overline{\text{CLR}}$ , $\overline{\text{PR}} - \text{Q}$ , $\overline{\text{Q}}$ )	$t_{\text{pLH}}$ $t_{\text{pHL}}$		3.3 ± 0.3	—	8.6	14.6	1.0	16.8	ns
			5.0 ± 0.5	—	5.8	8.3	1.0	9.6	
Maximum Clock Frequency	$f_{\text{MAX}}$		3.3 ± 0.3	45	90	—	45	—	MHz
			5.0 ± 0.5	80	150	—	80	—	
Input Capacitance	$C_{\text{IN}}$			—	5	10	—	10	pF
Power Dissipation Capacitance	$C_{\text{PD}}(1)$			—	85	—	—	—	

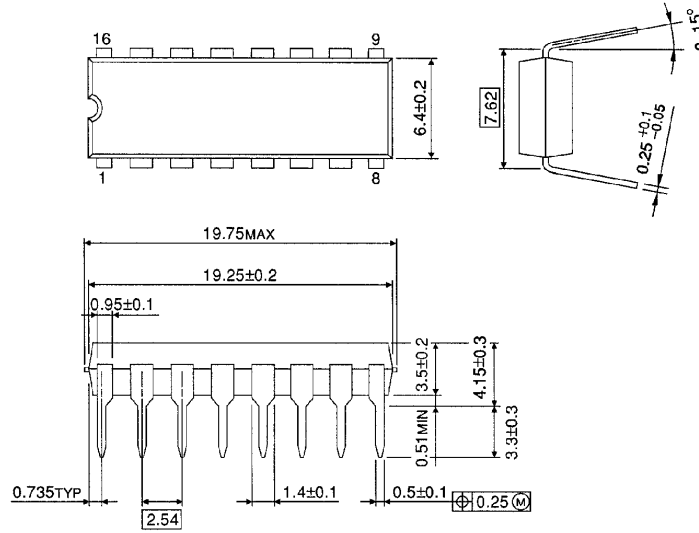
Note(1)  $C_{\text{PD}}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{\text{CC}}(\text{opr.}) = C_{\text{PD}} \cdot V_{\text{CC}} \cdot f_{\text{IN}} + I_{\text{CC}}/2 \text{ (per F/F)}$$

**DIP 16PIN PACKAGE DIMENSIONS (DIP16-P-300-2.54A)**

Unit in mm



Weight : 1.00g (Typ.)

**SOP 16PIN (200mil BODY) PACKAGE DIMENSIONS (SOP16-P-300-1.27)**

Unit in mm

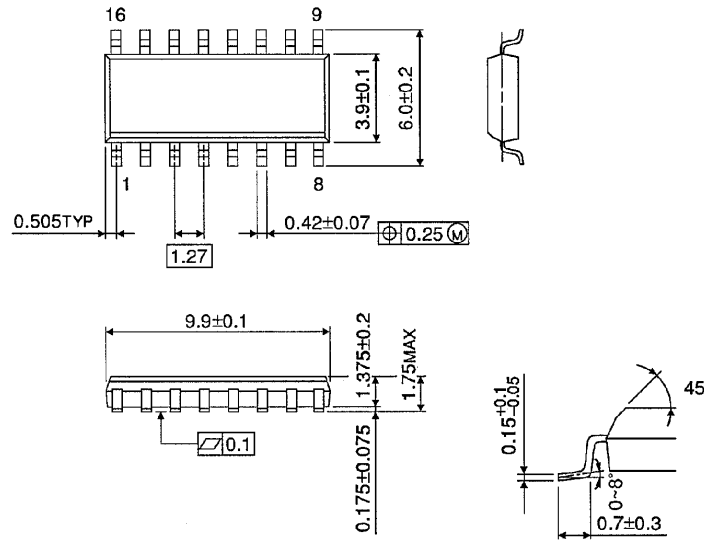


Weight : 0.18g (Typ.)

SOP 16PIN (150mil BODY) PACKAGE DIMENSIONS (SOL16-P-150 -1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)

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